

耐O₂，無添加物之超高潔淨型產品 Endurable for O₂ plasma, non-filler & ultra clean performance

- 透明無添加物的特殊材料，非常適合使用在Etch, Ashing等電漿環境。針對O₂, 氟化氣體等離子有非常優異的抵抗表現，不論是在動態件或是靜態件上的應用，例如Slit Valve, Chamber Lid, Gate Valve等都可以完美的對應

Transparent non-filler type material for Etch, Ashing and plasma application. It offers excellent resistance against O₂, Fluorine plasma both in static and dynamic application such as Slit Valve, Chamber Lid, Gate Valve.



- 超高氟含量與高耐溫，適合嚴苛的製程環境
High fluoro content & high temp. resistance, suitable for harsh environment

ea 特性與優點 FEATURE

- 對於O₂電漿環境有良好的耐受性
Resistant to O₂ plasma
- 良好的不沾粘性
Good non-stick characteristics
- 低的元素析出性
Low level of extractable trace elements
- 對各式化學溶劑有極優良的抗性
Excellent resistance to solvents and chemicals

ea 典型物理特性 PROPERTY

硬度(Shore A)	63
顏色(Color)	Translucent
模數(100 % Modulus, Mpa)	3.5
拉伸強度(Tensile strength at Break, Mpa)	11.3
延伸率(Elongation at Break, %)	210
壓縮變形率(Compression set 70 hr @ 250°C)	12.1
建議最高連續使用溫度(Temp., °C)	300

ea 建議應用位置 APPLIED POSITION

- 反應槽密封件(Chamber Seals)
- 管線接頭密封件(Fitting Seals)
- 氣體管線密封件(Gas Inlet/Outlet Pumping Line Seals)
- 閥件密封件(Valve Seals)
- 閥門開關(Slit valve doors)

ea 建議應用製程 APPLIED PROCESS

- 乾式蝕刻(Dry Etch)
- 濕式蝕刻(Wet Etch Acid, Base)
- 擴散(Diffusion)
- 離子植入(Ion Implant)
- 快速回火(RTP)
- 濕式去光阻(Wet Stripping Solvents)
- 濕式清潔(Wet Cleaning UPDI)